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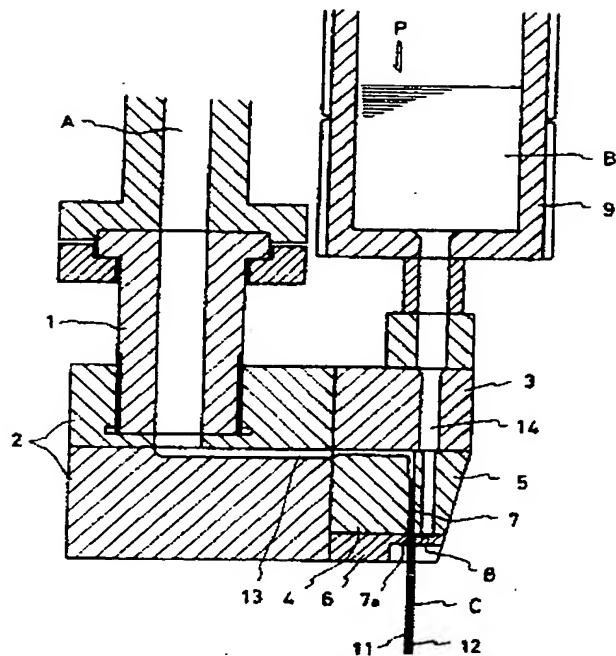
APPLICATION DATE : 29-09-80
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TITLE : METHOD AND APPARATUS FOR
PRODUCING SYNTHETIC RESIN
MOLDED ARTICLE WITH ADHESIVE
LAYER



ABSTRACT : PURPOSE: To form an adhesive layer of uniform thickness at an adhesive surface of a synthetic resin molded article by a method wherein a layer of an adhesive is extruded through a nozzle in a die simultaneously with producing a synthetic resin molded article.

CONSTITUTION: A synthetic resin A extruded from an extruder is rectified by a slit 7 provided in a nozzle 4, 5 after it is passed through a joint 1 and a passage 13, and it is continuously extruded as the synthetic resin molded article C of a desired shape through a molding slit 7a of a plate 6. On the other hand, the adhesive B in a tank 9 is made to be laminar by introducing it into a slit 8 for molding the adhesive layer through a passage 14 provided in the nozzles 3, 5 and is joined to the molded synthetic resin 11 passing through the slit 7a to form the adhesive layer 12 as one body with the molded resin 11, followed by extruding the body through the slit 7 to obtain the synthetic molded article C which has the adhesive layer 12 on one side of the molded synthetic resin 11.

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